

SGH20N120RUF

Short Circuit Rated IGBT

General Description

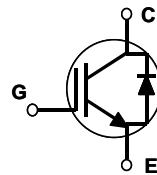
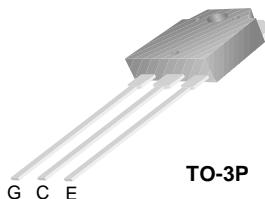
Fairchild's Insulated Gate Bipolar Transistor(IGBT) RUF series provides low conduction and switching losses as well as short circuit ruggedness. RUF series is designed for the applications such as motor control, UPS and general inverters where short-circuit ruggedness is required.

Features

- Short Circuit Rated 10 μ s @ $T_C = 100^\circ\text{C}$, $V_{GE} = 15\text{V}$
- High Speed Switching
- Low Saturation Voltage : $V_{CE(\text{sat})} = 2.3\text{ V}$ @ $I_C = 20\text{A}$
- High Input Impedance
- CO-PAK, IGBT with FRD : $t_{rr} = 80\text{ns}$ (typ.)

Application

AC & DC Motor Controls, General Purpose Inverters, Robotics, Servo Controls



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Description	SGH20N120RUF	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 25	V
I_C	Collector Current @ $T_C = 25^\circ\text{C}$	32	A
	Collector Current @ $T_C = 100^\circ\text{C}$	20	A
$I_{CM(1)}$	Pulsed Collector Current	60	A
I_F	Diode Continuous Forward Current @ $T_C = 100^\circ\text{C}$	20	A
I_{FM}	Diode Maximum Forward Current	120	A
T_{SC}	Short Circuit Withstand Time @ $T_C = 100^\circ\text{C}$	10	μs
P_D	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	230	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	92	W
T_J	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temp. for soldering PurPoses, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

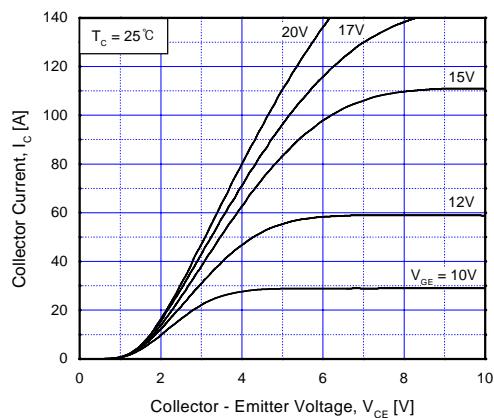
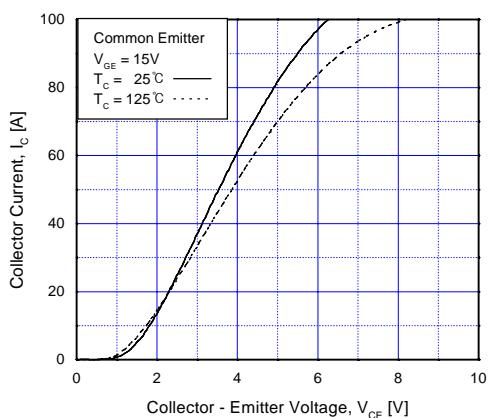
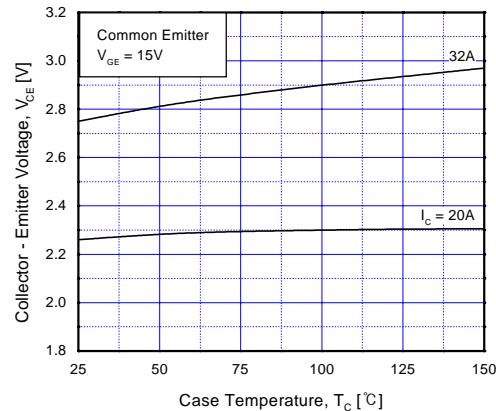
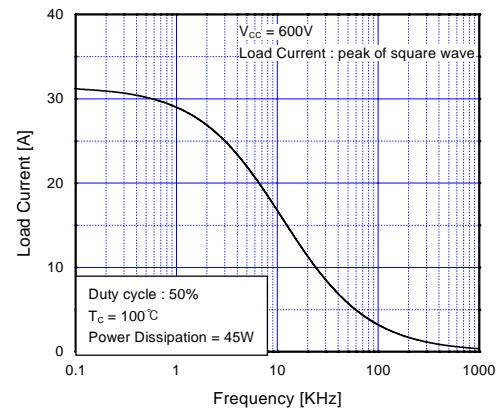
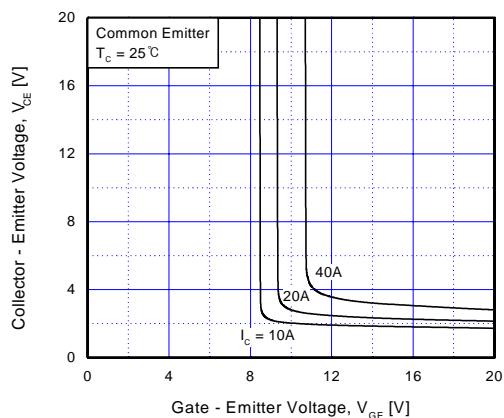
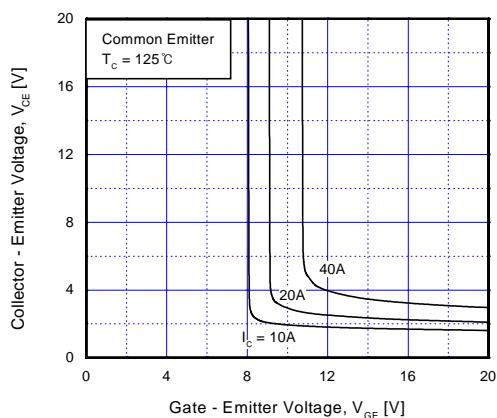
Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(\text{IGBT})$	Thermal Resistance, Junction-to-Case	--	0.54	$^\circ\text{C}/\text{W}$
$R_{\theta JC}(\text{DIODE})$	Thermal Resistance, Junction-to-Case	--	0.84	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	40	$^\circ\text{C}/\text{W}$

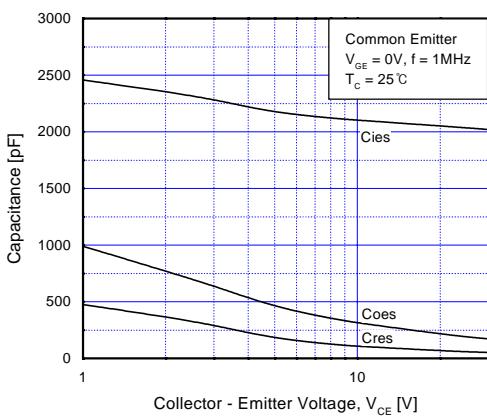
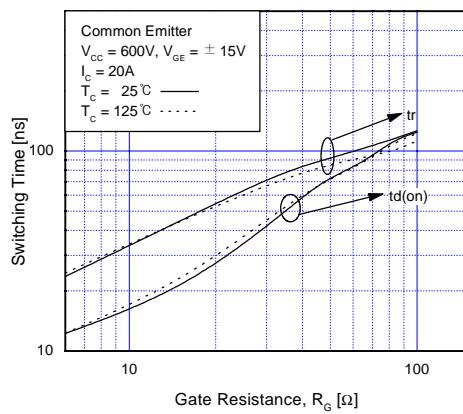
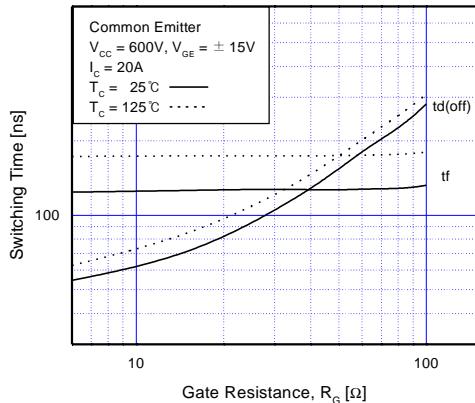
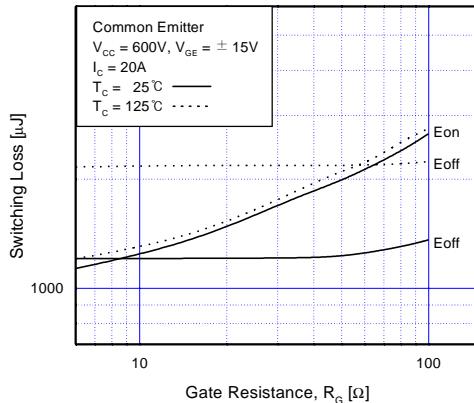
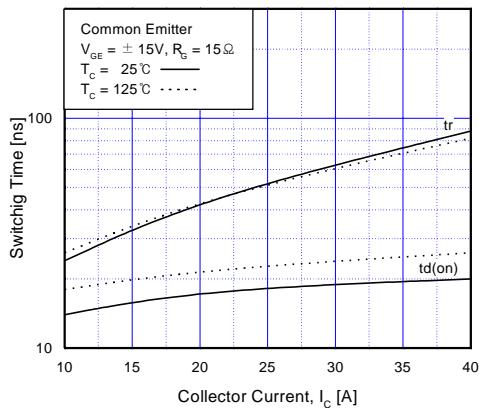
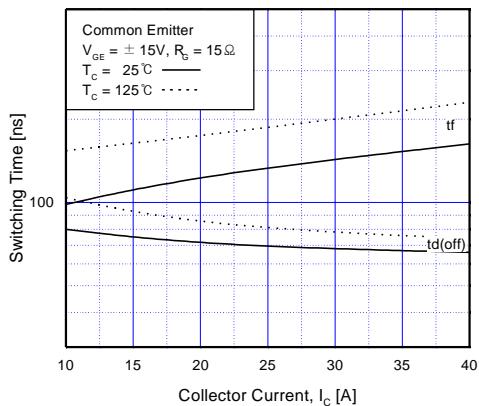
Electrical Characteristics of IGBT $T_C = 25^\circ\text{C}$ unless otherwise noted

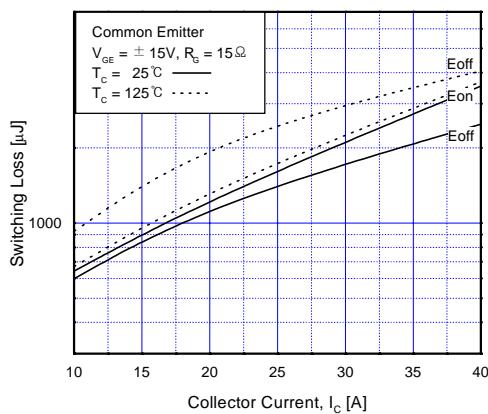
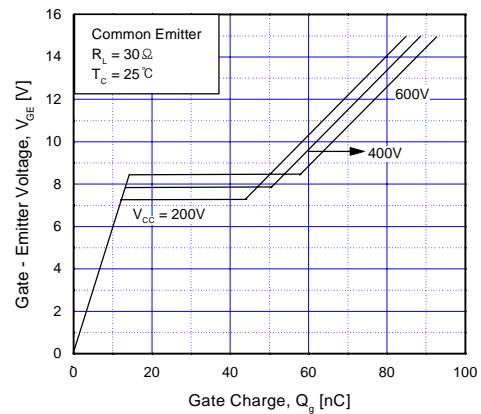
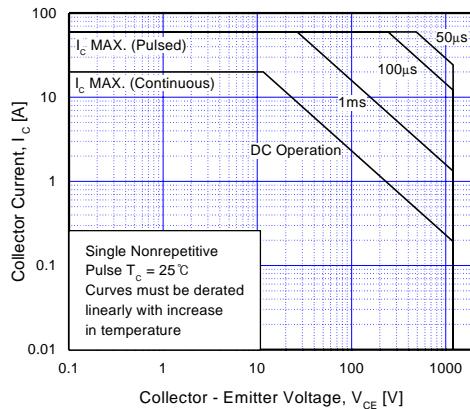
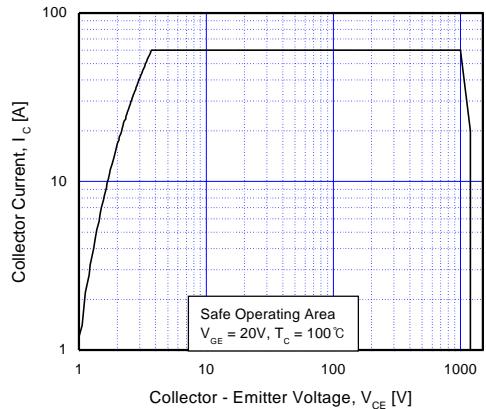
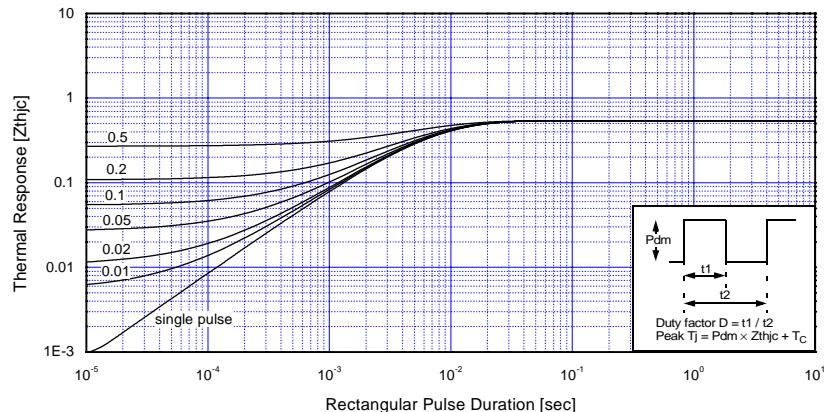
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV_{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0\text{V}, I_C = 1\text{mA}$	1200	--	--	V
$\Delta B_{VCES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	$V_{GE} = 0\text{V}, I_C = 1\text{mA}$	--	0.6	--	$\text{V}/^\circ\text{C}$
I_{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0\text{V}$	--	--	1	mA
I_{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0\text{V}$	--	--	± 100	nA
On Characteristics						
$V_{GE(\text{th})}$	G-E Threshold Voltage	$I_C = 20\text{mA}, V_{CE} = V_{GE}$	3.5	5.5	7.5	V
$V_{CE(\text{sat})}$	Collector to Emitter Saturation Voltage	$I_C = 20\text{A}, V_{GE} = 15\text{V}$	--	2.3	2.7	V
		$I_C = 32\text{A}, V_{GE} = 15\text{V}$	--	2.8	--	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	$V_{CE} = 30\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	--	2000	--	pF
C_{oes}	Output Capacitance		--	170	--	pF
C_{res}	Reverse Transfer Capacitance		--	60	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600\text{ V}, I_C = 20\text{A}, R_G = 15\Omega, V_{GE} = 15\text{V}, \text{Inductive Load}, T_C = 25^\circ\text{C}$	--	30	--	ns
t_r	Rise Time		--	60	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	70	130	ns
t_f	Fall Time		--	150	200	ns
E_{on}	Turn-On Switching Loss		--	1.30	--	mJ
E_{off}	Turn-Off Switching Loss		--	1.30	--	mJ
E_{ts}	Total Switching Loss		--	2.60	3.65	mJ
$t_{d(on)}$	Turn-On Delay Time		--	30	--	ns
t_r	Rise Time		--	70	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	90	165	ns
t_f	Fall Time	$V_{CC} = 600\text{ V}, I_C = 20\text{A}, R_G = 15\Omega, V_{GE} = 15\text{V}, \text{Inductive Load}, T_C = 125^\circ\text{C}$	--	200	270	ns
E_{on}	Turn-On Switching Loss		--	1.50	--	mJ
E_{off}	Turn-Off Switching Loss		--	2.00	--	mJ
E_{ts}	Total Switching Loss		--	3.50	5.08	mJ
T_{sc}	Short Circuit Withstand Time	$V_{CC} = 600\text{ V}, V_{GE} = 15\text{V} @ T_C = 100^\circ\text{C}$	10	--	--	μs
Q_g	Total Gate Charge	$V_{CE} = 600\text{ V}, I_C = 20\text{A}, V_{GE} = 15\text{V}$	--	95	140	nC
Q_{ge}	Gate-Emitter Charge		--	15	25	nC
Q_{gc}	Gate-Collector Charge		--	43	65	nC
L_e	Internal Emitter Inductance	Measured 5mm from PKG	--	14	--	nH

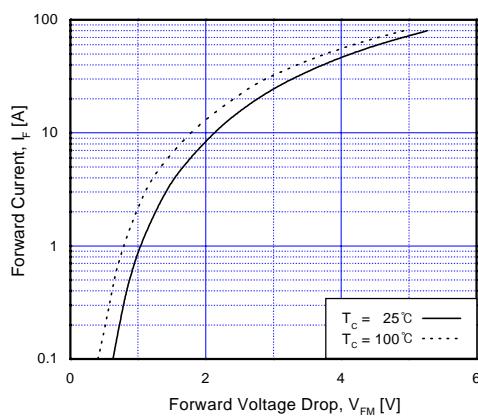
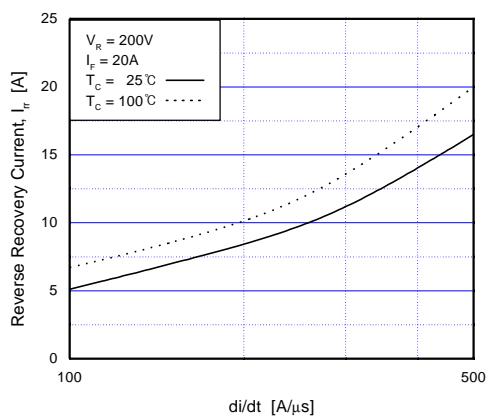
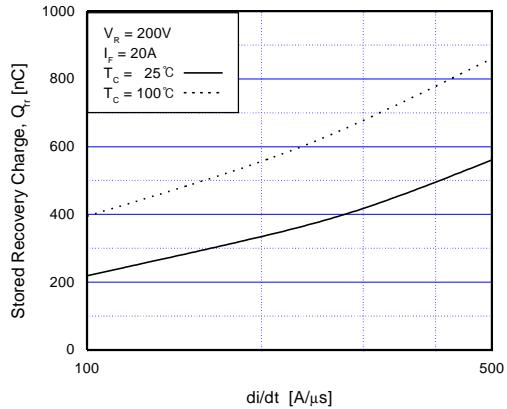
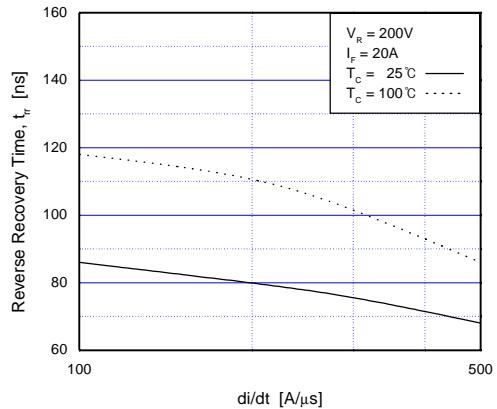
Electrical Characteristics of DIODE $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{FM}	Diode Forward Voltage	$I_F = 20\text{A}$	$T_C = 25^\circ\text{C}$	--	2.8	3.5
			$T_C = 100^\circ\text{C}$	--	2.5	--
t_{rr}	Diode Reverse Recovery Time	$I_F = 20\text{A}$ $dI/dt = 200\text{ A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	--	80	110
			$T_C = 100^\circ\text{C}$	--	95	--
I_{rr}	Diode Peak Reverse Recovery Current	$I_F = 20\text{A}$ $dI/dt = 200\text{ A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	--	8.0	10.0
			$T_C = 100^\circ\text{C}$	--	9.5	--
Q_{rr}	Diode Reverse Recovery Charge	$I_F = 20\text{A}$ $dI/dt = 200\text{ A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	--	320	500
			$T_C = 100^\circ\text{C}$	--	450	--


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics

Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency

Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. V_{GE}


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs. Gate Resistance

Fig 9. Turn-Off Characteristics vs. Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance

Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics

Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA

Fig 17. Transient Thermal Impedance of IGBT

**Fig 18. Forward Characteristics****Fig 19. Reverse Recovery Current****Fig 20. Stored Charge****Fig 21. Reverse Recovery Time**

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